

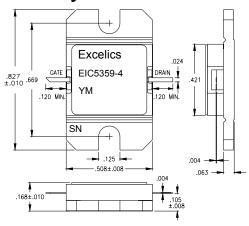


ISSUED 5/15/2006

5.3-5.9 GHz 4-Watt Internally Matched Power FET

FEATURES

- 5.3-5.9GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +36.5 dBm Output Power at 1dB Compression
- 10.5 dB Power Gain at 1dB Compression
- 34% Power Added Efficiency
- **Hermetic Metal Flange Package**



ELECTRICAL CHARACTERISTICS (Ta = 25°C)



Caution! ESD sensitive device.

SYMBOL	PARAMETERS/TEST CONDITIONS ¹	MIN	TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compression $f = 5.3-5.9GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100 \text{mA}$	35.5	36.5		dBm
G _{1dB}	Gain at 1dB Compression $f = 5.3-5.9GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100\text{mA}$	9.5	10.5		dB
ΔG	Gain Flatness $f = 5.3-5.9GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100\text{mA}$			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100 \text{mA}$ f = 5.3-5.9GHz		34		%
Id _{1dB}	Drain Current at 1dB Compression f = 5.3-5.9GHz		1200	1400	mA
IM3	Output 3rd Order Intermodulation Distortion Δf =10MHz 2-Tone Test. Pout=25.5 dBm S.C.L Vds = 10 V, I _{DSQ} ≈ 65% I _{DSS} f = 5.9GHz	-43	-46		dBc
I _{DSS}	Saturated Drain Current $V_{DS} = 3 V$, $V_{GS} = 0 V$		2000	2500	mA
V_P	Pinch-off Voltage $V_{DS} = 3 \text{ V}, I_{DS} = 20 \text{ mA}$		-2.5	-4.0	V
R _{TH}	Thermal Resistance ³		5.5	6	°C/W

Note: 1) Tested with 100 Ohm gate resistor.

ABSOLUTE MAXIMUM RATING^{1,2}

SYMBOLS	PARAMETERS	ABSOLUTE ¹	CONTINUOUS ²
Vds	Drain-Source Voltage	15	10V
Vgs	Gate-Source Voltage	-5	-4V
lgsf	Forward Gate Current	43.2mA	14.4mA
lgsr	Reserve Gate Current	-7.2mA	-2.4mA
Pin	Input Power	35.5dBm	@ 3dB Compression
Tch	Channel Temperature	175°C	175°C
Tstg	Storage Temperature	-65 to +175 °C	-65 to +175 °C
Pt	Total Power Dissipation	25W	25W

Note: 1. Exceeding any of the above ratings may result in permanent damage.
2. Exceeding any of the above ratings may reduce MTTF below design goals.

²⁾ S.C.L. = Single Carrier Level.

³⁾ Overall Rth depends on case mounting.